

# Chip Bead For High Current

## CIC21 Series (2012/ EIA 0805)

## APPLICATION

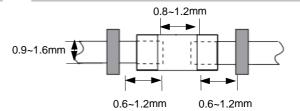
Noise Suppression in power line

### **FEATURES**

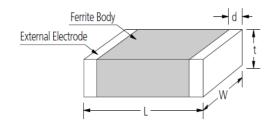
• CIC series is used for high current. )



### RECOMMENDED LAND PATTERN



### **DIMENSION**



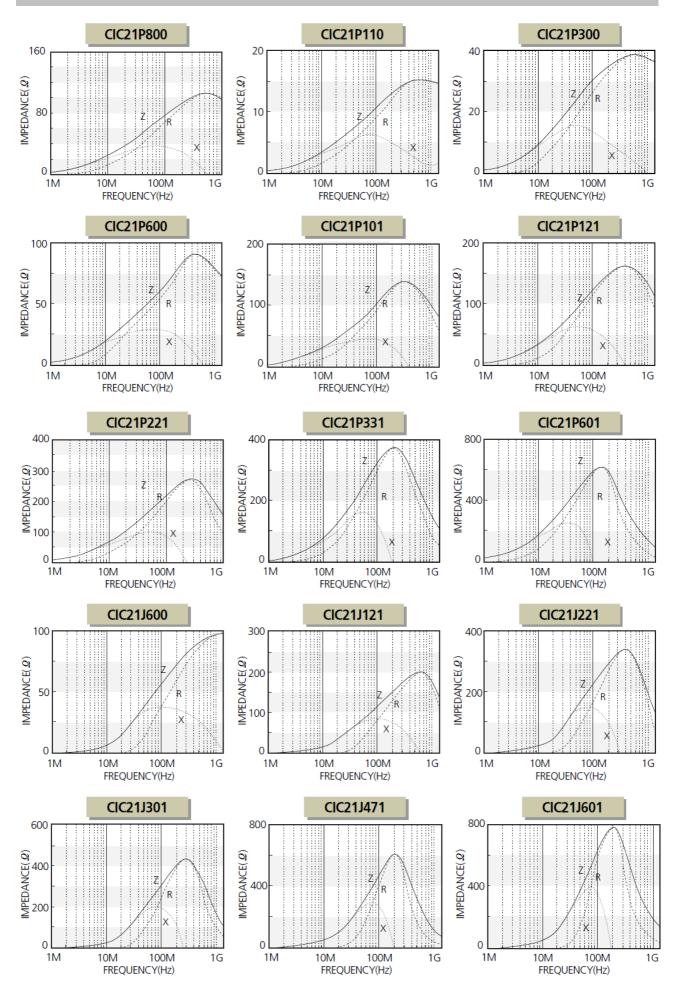
Туре	Dimension [mm]				
	L	W	t	d	
21	2.0±0.2	1.25±0.2	0.9±0.2	0.5+0.2	

### **DESCRIPTION**

Part no.	Thickness (mm)	Impedance (Ω)±25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIC21P110	0.90±0.2	11	0.05	6000
CIC21P300	0.90±0.2	30	0.015	3000
CIC21P600	0.90±0.2	60	0.025	3000
CIC21P800	0.90±0.2	80	0.025	2500
CIC21P101	0.90±0.2	100	0.02	2000
CIC21P121	0.90±0.2	120	0.05	2000
CIC21P221	0.90±0.2	220	0.035	3200
CIC21P331	0.85±0.2	330	0.05	2000
CIC21P601	0.90±0.2	600	0.15	1000
CIC21J600	0.90±0.2	60	0.03	3800
CIC21J121	0.90±0.2	120	0.05	2500
CIC21J221	0.90±0.2	220	0.05	1500
CIC21J301	0.90±0.2	300	0.10	1500
CIC21J471	0.90±0.2	470	0.08	1500
CIC21J601	0.90±0.2	600	0.15	1000



### CHARACTERISTIC DATA







110 (3) (4) (5)

(1) Chip Beads

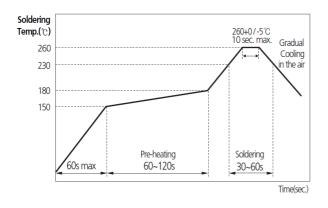
(2) For High current(C:~3A)

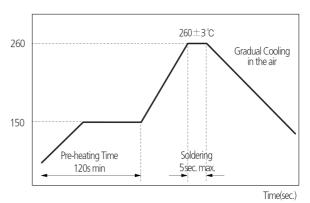
(3) Dimension

- (4) Material Code
- (5) Nominal impedance (110:11 $\Omega$ , 221:220 $\Omega$ )
- (6) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (7) Packaging(C:paper tape, E:embossed tape)

### **REFLOW SOLDERING**

## FLOW SOLDERING





Packaging Style	Quantity(pcs/reel)	
Embossed Taping	4000	

Any data in this sheet are subject to change, modify or discontinue without notice.

The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.